

**AMENDMENTS TO THE SPECIFICATION:**

Please amend paragraph [0006] of the Substitute Specification as follows:

A method of manufacturing an electronic component according to a preferred embodiment of the present invention includes a mounting step including mounting on a collective mounting substrate a plurality of electronic functional elements, each having a substrate and an electronic functional portion provided on the substrate, an arranging step including arranging a resin film on the electronic functional elements mounted on the collective mounting substrate, a reduced-pressure packing step for putting the electronic functional elements and the resin film mounted on the collective packing mounting substrate in a bag with a gas-barrier property, and hermetically sealing the contents inside the bag by closing the opening of the bag after depressurizing the inside of the bag ~~to seal the contents inside~~, a sealing step including sealing the electronic functional elements with a sealing resin member formed from the resin film by causing the resin film to infiltrate between the electronic functional elements mounted on the reduced-pressure-packed collective mounting substrate, and a dividing step including dividing the collective mounting substrate having the resin-sealed electronic functional elements into individual electronic functional elements.

Please amend paragraph [0015] of the Substitute Specification as follows:

In the above-described manufacturing method, the sealing step may further include a thermo-compression bonding step for heating the resin film to ~~eure~~ soften the resin film and for applying pressure to the resin film via a roller or a press machine or other suitable pressure applying element. According to the above-described method, applying pressure to the resin film via the roller or pressure applying element enables sealing by the resin film to be more rapid.